

Liquid-cooled conduction enclosures

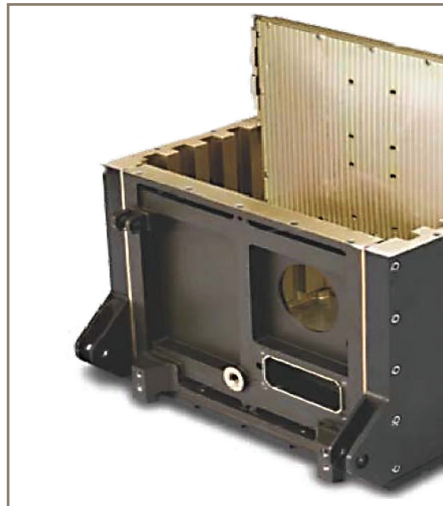
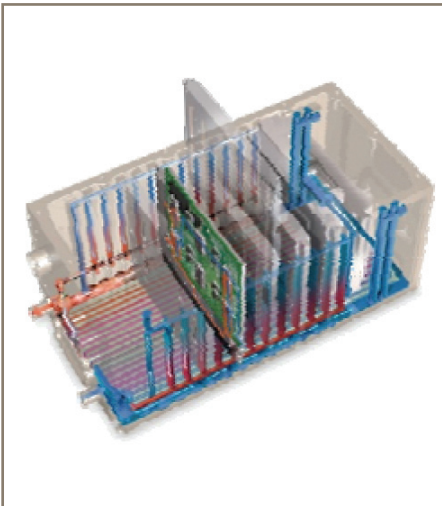
Description

The advanced liquid-cooled enclosures enable high-power density embedded electronics in ruggedized military, aerospace, industrial, and commercial applications.

Top-loaded enclosure uses a conduction-cooled card cage. Liquid-cooled chassis side walls enable cards in excess of 200 watts.

This rugged enclosure is adaptable for different applications, with VPX, OpenVPX, VXS, VME64x, Compact PCI, or hybrid type backplanes.

Utilizing Parker's proprietary Macrospray™ technology, these enclosures provide three times the watt/area capacity of traditional designs, or the same watt/area with 1/3 the flow rate.



Product Highlights

- All VITA 58 sizes available and easily configured for any application
- Embedded coldplates in adjacent walls are available for direct cooling of high-heat components (e.g. power supply)
- Compatible with most dielectric (e.g. PAO/fluorocarbon) or non-dielectric (e.g. EGW/PGW) cooling fluids
- Accommodates two-level field maintenance
- Options available to enable use of liquid flow through modules which can be attached to cards

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